

HSP

NOTES:

Current Rating: 3.0AMP
 Withstand Voltage: 500V AC/DC
 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩMin
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact plating: Au or Sn over Ni
 Insulator Material: PA6T or PBT+30%G.F UL94V-0

Ordering Information

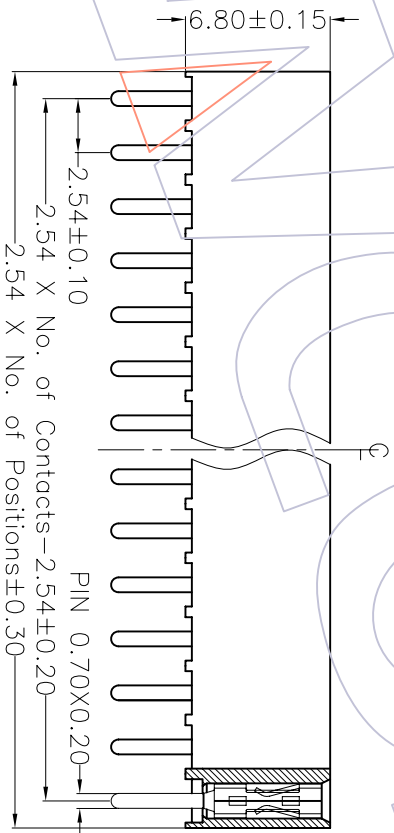
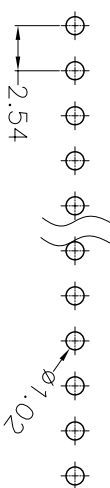
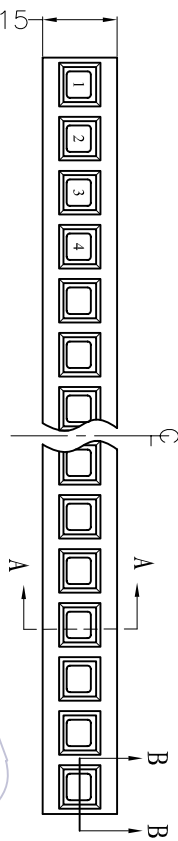
2168T - 1 XX S XX X UN T 1

No. of Pins per ROW: 52=40Pin

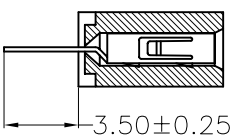
Contact Plating:
 CO=Gold Flash
 G1=5μ"Gold
 G2=5μ"Gold
 G3=10μ"Gold
 G4=15μ"Gold
 G5=30μ"Gold
 SP=Gold Flash,Tin
 S1=5μ"Gold,Tin
 S2=5μ"Gold,Tin
 S3=10μ"Gold,Tin
 S4=15μ"Gold,Tin
 S5=30μ"Gold,Tin
 SN=Tin

Insulator:
 A=PBT
 C=PA6T

Packing:
 T=Tube



SECTION: B-B



SECTION: A-A

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WEIXD	SCALE	UNIT	PART NO.	TITLE:
A0	08/03/12	NEW			XXX ±0.40 XXX ±0.25 XXX ±0.15	DESIGN CHECK	08.03.12	4:1	mm	2168T-1XXSXXUNT1	FH2.54 SINGLE 180° H=6.8 TOP ENTER
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle DIM	CHECK APPROVE		PROJ.		Customer NO.	
1					± .3° TOL						

WCON 维峰五金电子有限公司
 WAFER HARDWARE ELECTRONICS CO.,LTD

Recommended P.C.B Layout(TOP Side)
 (PCB BOARD TOLERANCE±0.05)